

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10534962			
<b>Filing Date:</b>	16-May-2005			
<b>Title of Invention:</b>	Circuit board, multi-layer wiring boards, method of producing circuit boards and method of producing multilayer wiring boards			
<b>First Named Inventor/Applicant Name:</b>	Masayoshi Kondo			
<b>Filer:</b>	Robert G. Weillacher/Susan Revell			
<b>Attorney Docket Number:</b>	033036.088			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Notice of appeal	1401	1	510	510
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 2 months with \$120 paid	1252	1	340	340
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>850</b>